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a	b	c	d	e	f	g + h + i
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columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly				
Layer-1	35 μ	Copper		} A1				
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125) 			
	100 μ	Prepreg						
	100 μ	Prepreg						
Layer-2	35 μ	Copper			} A2			
	410 μ	L-FR4						
Layer-3	35 μ	Copper					} B	
	100 μ	Prepreg						
	100 μ	Prepreg						
Layer-4	100 μ	Prepreg				} A1		
	35 μ	Copper						
Layer-5	35 μ	Copper						} A2
	410 μ	L-FR4						
Layer-99	35 μ	Copper						
	100 μ	Prepreg						
	100 μ	Prepreg						
Layer-99	100 μ	Prepreg		} A1				
	35 μ	Copper						
Layer-99	35 μ	Copper					} B	
	410 μ	L-FR4						

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